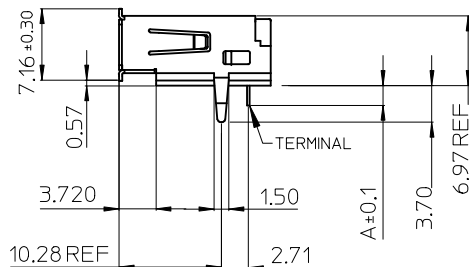
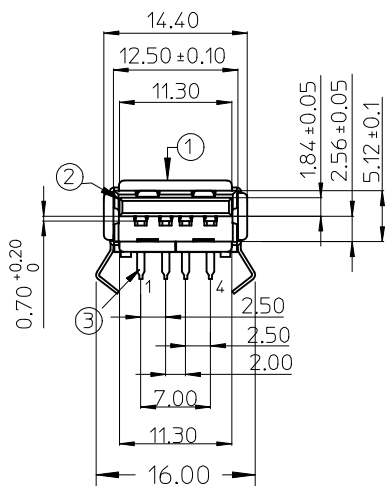
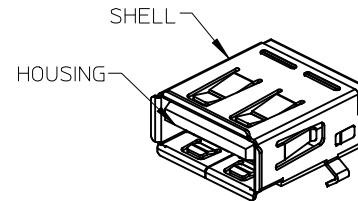


PCB LAYOUT (TOP VIEW)



NOTES:

1. MATERIAL:

- ① METAL SHELL: COPPER ALLOY.
- ② HOUSING: SEE CHART, 30% GLASS FIBER FILLED, UL94-V0.
- ③ TERMINAL: PHOSPHOR BRONZE

2. TERMINAL:

CONTACT AREA: (a) GOLD FLASH.

(b) GOLD (Au), THICKNESS=0.76µM/ 30µMCH MINIMUM.
 SOLDER TAIL: TIN PLATED, THICKNESS=1.9µM/ 75µMCH MINIMUM.
 UNDER PLATED: NICKEL (Ni), THICKNESS=1.25µM/50µMCH MINIMUM.
 METAL SHELL: SEE CHART.

3. RECOMMENDED PCB THICKNESS: SEE CHART

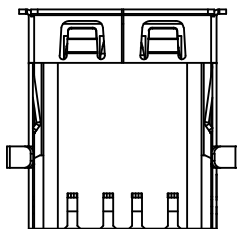
- 4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002
 FOR NON IR REFER TO PS-67643-003

5. TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.

- 6. TEST SUMMARY: FOR IR REFER TO TS-67643-002
 FOR NON IR REFER TO TS-67643-003

7. PACKAGE: REFER TO PK-67643-002

8. LEAD FREE AND ROHS COMPLIANT PRODUCT



REVISED EC NO: DRAWN: FYANG05 CHKD: APPR:	DESCRIPTION 2013/05/09	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		▽=0 ∇=0	mm	INCH	DRAWN BY IVY-LIN	DATE 2005/03/31	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)			
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± ---	ANGULAR ± 3 °		CHECKED BY ALL IN	DATE 2005/03/31				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 2		APPROVED BY WWSCHANG	DATE 2005/03/31	MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-67643-003		SHEET NO. 1 OF 2	

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P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK	
67643-0910	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS= 2.54μM/100μNCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR	
67643-1910	POLYESTER	WHITE			REFLOW PROCESS	
67643-2910	HIGH TEMPERATURE NYLON	BLACK			FOR IR	
67643-3910	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS	
67643-0911	POLYESTER	BLACK	GOLD PLATING 0.76μM/30μNCH		NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS= 2.00μM/80μNCH MINIMUM UNDER PLATE:NICKEL (Ni).	NON IR
67643-1911	POLYESTER	WHITE				REFLOW PROCESS
67643-2911	HIGH TEMPERATURE NYLON	BLACK				FOR IR
67643-3911	HIGH TEMPERATURE NYLON	WHITE				REFLOW PROCESS
PCB THICKNESS		1.60±0.05				
DIMENSION "A"		2.60				

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK	
67643-0930	HIGH TEMPERATURE NYLON	BLACK	GOLD FLASH	FOR IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS= 2.54μM/100μNCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR	
67643-1930	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS	
67643-0931	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 0.76μM /30μNCH			
67643-1931	HIGH TEMPERATURE NYLON	WHITE				
PCB THICKNESS		1.20±0.05				
DIMENSION "A"		2.00				

REVISED ECT NO: DRAWN:FYANG05 CHKD: APPR:	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY IVY-LIN	DATE 2005/03/31	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)		
			4 PLACES	± ---	± ---	CHECKED BY ALL IN	DATE 2005/03/31			
			3 PLACES	± ---	± ---	APPROVED BY WWSCHANG	DATE 2005/03/31	MOLEX INCORPORATED DOCUMENT NO. SD-67643-003		
			2 PLACES	± 0.25	± ---	MATERIAL NO.	SEE TABLE			
1 PLACE	± 0.25	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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